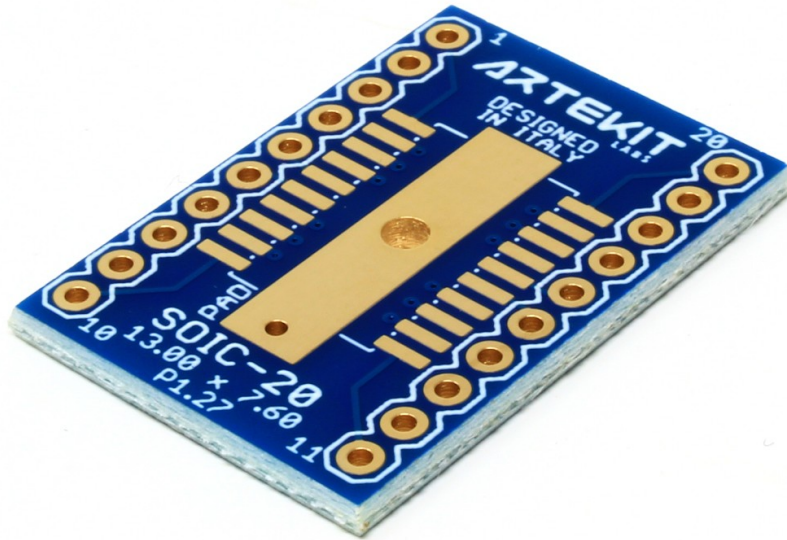


DA-SOIC20-13X7P127

SOIC-20 TO DIP ADAPTER – 13mm x 7.6mm – P1.27



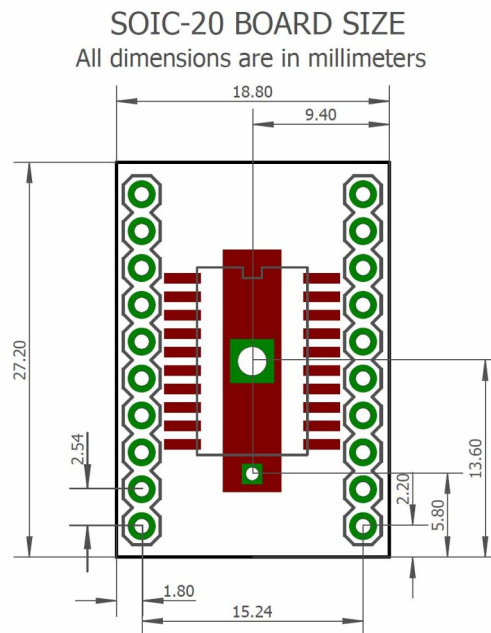
This adapter breaks out the pins of a component with SOIC-20 package (with a body of 13mm x 7.6mm and 1.27mm pin pitch) into a board with 0.1" (2.54mm) spaced pins.

This is a high quality PCB, with all the copper pads and contacts plated with Electroless Nickel Immersion Gold (ENIG) process, offering an excellent surface planarity and oxidation resistance.

The land pattern includes a central pad that can be used to dissipate heat from a high-power integrated circuit, like a motor controller or an audio amplifier. There is also a hole drilled through the central pad that can be used to drop some solder and ensure dissipation and conductivity up to the component. The central pad dimension is long enough and includes an extra hole that can be used to eventually wire a connection to it.

| Specifications | |
|---------------------|-----------------|
| Supported packages | SOIC-20 |
| Package body size | 13mm x 7.6mm |
| Component pin pitch | 1.27mm |
| Board pin pitch | 2.54mm (0.1") |
| Temperature rating | -25°C to +125°C |
| Material | FR4 |
| RoHS compliant | Yes |

Board dimensions



Land pattern dimensions

